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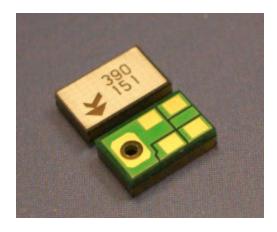








"Zero Height" Amplified SiSonicTM Microphone Specification



Knowles Acoustics 1151 Maplewood Drive Itasca, IL 60143

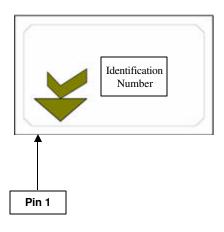




1. DESCRIPTION AND APPLICATION

- 1.1 Description
 Zero Height Amplified Surface Mount Silicon Microphone
- 1.2 Application
 Hand held telecommunication devices

2. PART MARKING



Identification Number Convention

S 1 2 3

4 5 6

S: Manufacturing Location

"S" – Knowles Electronics Suzhou Suzhou, China

"No Alpha Character" – Knowles Electronics Itasca Itasca, IL USA

"E" - Engineering Samples

Digits 1 – 6: Job Identification Number

3. TEMPERATURE RANGE

3.1 Operating Temperature Range: -40°C to +100°C

3.2 Storage Temperature Range: -40°C to +100°C

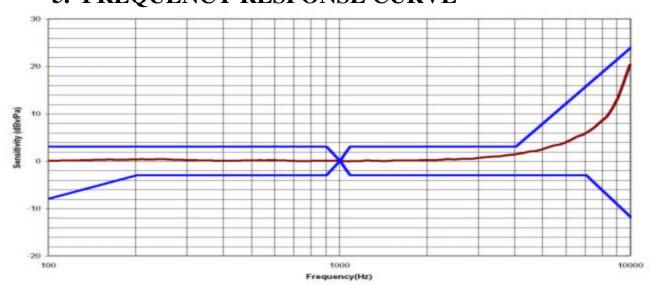




4. ACOUSTIC & ELECTRICAL SPECIFICATIONS

| | Symbol | Condition | Limits | | | Unit |
|------------------------------------|------------------|--|--------|------|-------|---------|
| | Symbol | Condition | Min. | Nom. | Max. | Onit |
| Directivity | | Omni-directional | | | | |
| Sensitivity | S | @ 1kHz (0dB=1V/Pa) | -26 | -22 | -18 | dB |
| Output impedance | Z _{OUT} | @ 1kHz (0dB=1V/Pa) | n/a | n/a | 100 | Ω |
| Current Consumption | I _{DSS} | across 1.5 to 5.5 volts | 0.100 | n/a | 0.350 | mA |
| Signal to Noise Ratio | S/N | @ 1kHz (0dB=1V/Pa) | 55 | 59 | n/a | dB |
| Supply Voltage | Vs | | 1.5 | n/a | 5.5 | V |
| Typical Input Referred Noise | ENL | A-weighted | n/a | 35 | n/a | dBA SPL |
| Sensitivity Loss across Voltage | | Change in sensitivity over 5.5v to 1.5v No Change Across Voltage Range | | dB | | |
| Maximum Input Sound Level | | At 100dB SPL, THD < 1% At 115dB SPL, THD = < 10% | | | dB | |
| Contact Resistance | | | | | 100 | Ohms |

5. FREQUENCY RESPONSE CURVE

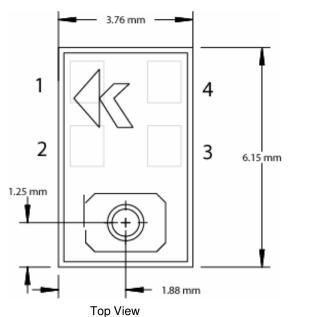




Revision: A 3 of 11



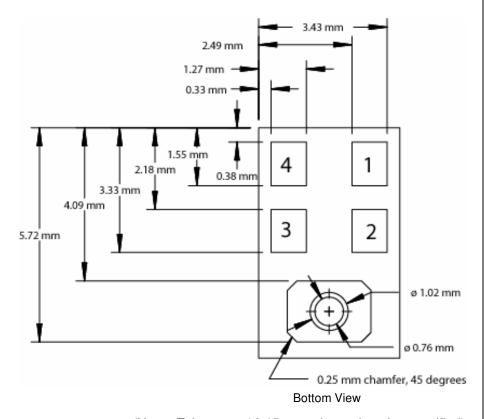
6. MECHANICAL SPECIFICATIONS





| <u>ltem</u> | <u>Dim.</u> | <u>Tol.</u> (+/-) | <u>Units</u> | |
|-------------|-------------|----------------------|--------------|--|
| Height | 1.65 | +0.20 -0.10 | mm | |
| Length | 6.15 | 0.10 | mm | |
| Width | 3.76 | 0.10 | mm | |
| Weight | 0.09 | grams | | |
| Coplanarity | < 0.1 | | mm | |

| Pin Output | | | |
|----------------|--------------|--|--|
| Pin # Function | | | |
| 1 | Output | | |
| 2 | Gain Control | | |
| 3 | Ground | | |
| 4 | Power | | |



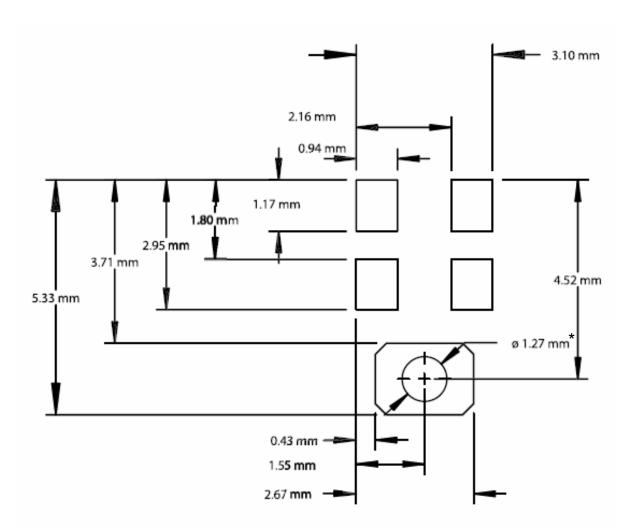
(Note: Tolerance +/-0.15mm unless otherwise specified)







7. RECOMMENDED CUSTOMER LAND PATTERN

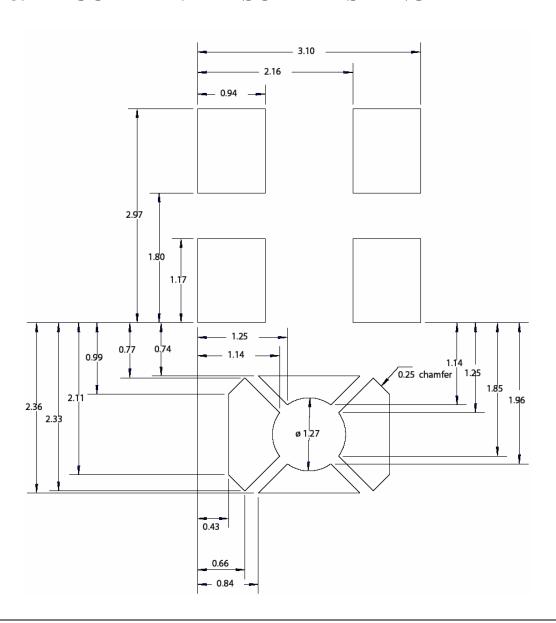


* Note: Minimum PCB Hole Diameter: 1.02 mm





8. RECOMMENDED SOLDER STENCIL PATTERN

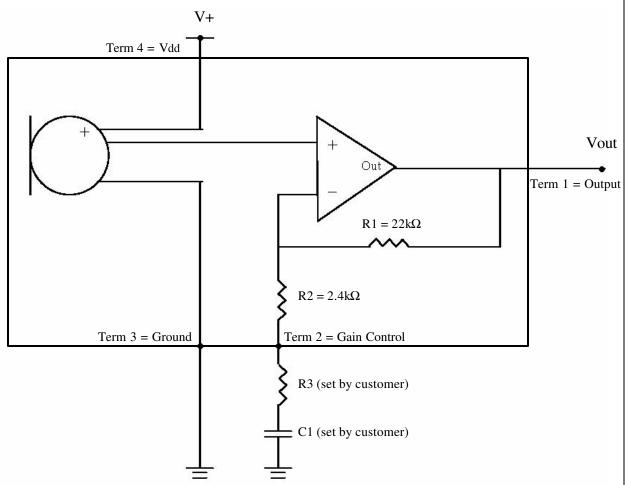


Notes:

- The design requires that an acoustic seal be established between the SiSonic and customer PCB. This is accomplished via a solder seal.
- Solder Stencil Thickness = 0.127 min to 0.178 max
- Stencil Material = Stainless Steel



9. RECOMMENDED INTERFACE CIRCUIT



| Desired Gain | Pin 2 Termination Method | | |
|------------------|---|--|--|
| Unity Gain (0dB) | Tie Terminal 2 directly to Output (Terminal 1). | | |
| 20dB Gain | Tie Terminal 2 through C1 (0.47uF) to Ground. | | |
| Adjustable Gain | Add R3 and C1. Use formulas provided to calculate settings, or contact Knowles for support. | | |

Setting Gain Formulas:

Gain of non-inverting Op-Amp is determined as:

 \implies G= 1+ {R1 / (R2 + R3)} Gain(dB) = 20 * log(G)

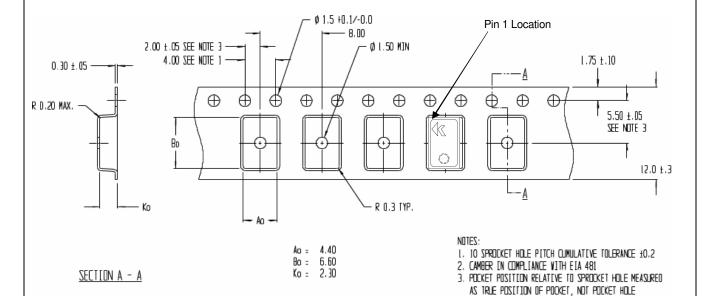
High-pass-filter Corner Frequency:

 \longrightarrow C.F. = 1 / { 2* p* (R2 + R3) * C1}





10. PACKAGING DETAIL



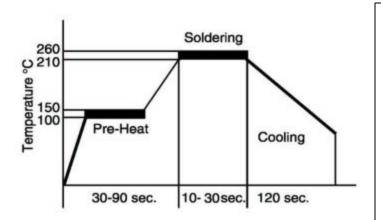
| Model Number | Suffix | <u>Reel</u> <u>Diameter</u> | <u>Qty per</u> <u>Reel</u> |
|--------------|--------|--------------------------------|-------------------------------|
| SP0103BE3 | -5 | 7" | 900 |
| SP0103BE3 | -4 | 13" | 3,600 |

| Tape & Reel | Available in 13" and 7" diameter. |
|------------------|---|
| Leader Length | 800mm or minimum of 100 empty pockets |
| Label | Label applied to external package and direct to reel. Per JEDEC. |
| Empty Units | No consecutive empty pockets; No more than 3 empty pockets per reel. (Does not include empty pockets for leader/follower) |





11. SOLDER REFLOW PROFILE



Notes:

- Maximum condition = 260 C for 30 seconds.
- 2. <u>Do not pull a vacuum</u> over the port hole of the microphone. Pulling a vacuum over the port hole can damage the device.
- 3. <u>Do not board wash</u> after the reflow process. Board washing and cleaning agents can damage the device. Do not expose to ultrasonic processing or cleaning.
- 4. Number of Reflow = recommend no more than 2 cycles.

12. ADDITIONAL NOTES

- (A) Packaging (reference SiSonic_Packaging_Spec.pdf)
- (B) Shelf life: Twelve (12) months when devices are to be stored in factory supplied, unopened moisture sensitivity bag under environmental conditions of 30°C, 60% R.H.
- (C) Exposure: Devices should not be exposed to high humidity, high temperature environment. Customer should follow standard baking times as stated in JEDEC J-STD-033A, reference Class 2A.

Out of bag: 90 days out of ESD moisture sensitive bag, assuming 30C/60% RH as maximum.

Baking Condition: After 90 days, refer to JEDEC J-STD-033A for recommend baking times and temperatures.







13. RELIABILITY SPECIFICATIONS

Note: After test conditions are performed, the sensitivity of the microphone shall not deviate more than 3dB from its initial value.

| Test | Description | | |
|------------------------------------|---|--|--|
| Thermal Shock | Microphone unit must operate when exposed to air-to-air thermal shock 100 cycles, from -40°C to +125°C. (IEC 68-2-4), | | |
| High Temperature Storage Test | Microphone unit must maintain sensitivity after storage at +105℃ for 1,000 hours. (IEC 68-2-2 Test Ba) | | |
| Low Temperature Storage Test | Microphone unit must maintain sensitivity after storage at –40°C for 1,000 hours. (IEC 68-2-1 Test Aa) | | |
| High Temperature Operating Test | Microphone unit must operate within sensitivity specifications for 1,000 hours at 105°C. (IEC 68-2-2 Test Ba) | | |
| Low Temperature Operating Test | Microphone unit must operate within sensitivity specifications for 1,000 hours at –40°C. (IEC 68-2-1 Test Aa) | | |
| Humidity Test | Tested under Bias at 85°C/85% R.H. for 1,000 hours. (JESD22-A101A-B) | | |
| Vibration Test | Microphone unit must operate under test condition: 4 cycles, from 20 to 2,000 Hz in each direction (x,y,z), 48 minutes, using peak acceleration of 20 G (+20%, -0%). (MIL 883E, method 2007.2, A) | | |
| Electrostatic Discharge | Tested to 8kV direct contact discharge or 15kV air discharge as specified by IEC 1000-4-2, level 3 and level 4. | | |
| Reflow | Microphone is tested to 5 passes through reflow oven, with microphone mounted upside-down under conditions of 260°C for 30 seconds maximum. | | |
| Mechanical Shock | Microphone must operate after exposure to shock test of 10,000 G per IEC 68-2-27, Ea. | | |





14. SPECIFICATION REVISIONS

| Revision | Detailed Specification Changes | Date |
|----------|--------------------------------|----------|
| А | Initial Release | 12-01-04 |
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